

SOT929-1

plastic low profile fine-pitch ball grid array package; 272 balls; body 15 x 15 x 1 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA272
Package type industry code	LFBGA272
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-205
Mounting method type	S (surface mount)
Issue date	21-12-2005

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		14.9	-	15	15.1	mm
E	package width		14.9	-	15	15.1	mm
A	seated height		[tbd]	-	1.5	1.5	mm
A ₂	package height		0.95	-	1	1.1	mm
n ₂	actual quantity of termination		-	-	272	-	



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2. Package outline

LFBGA272: plastic low profile fine-pitch ball grid package; 272 balls; body 15 x 15 x 1 mm

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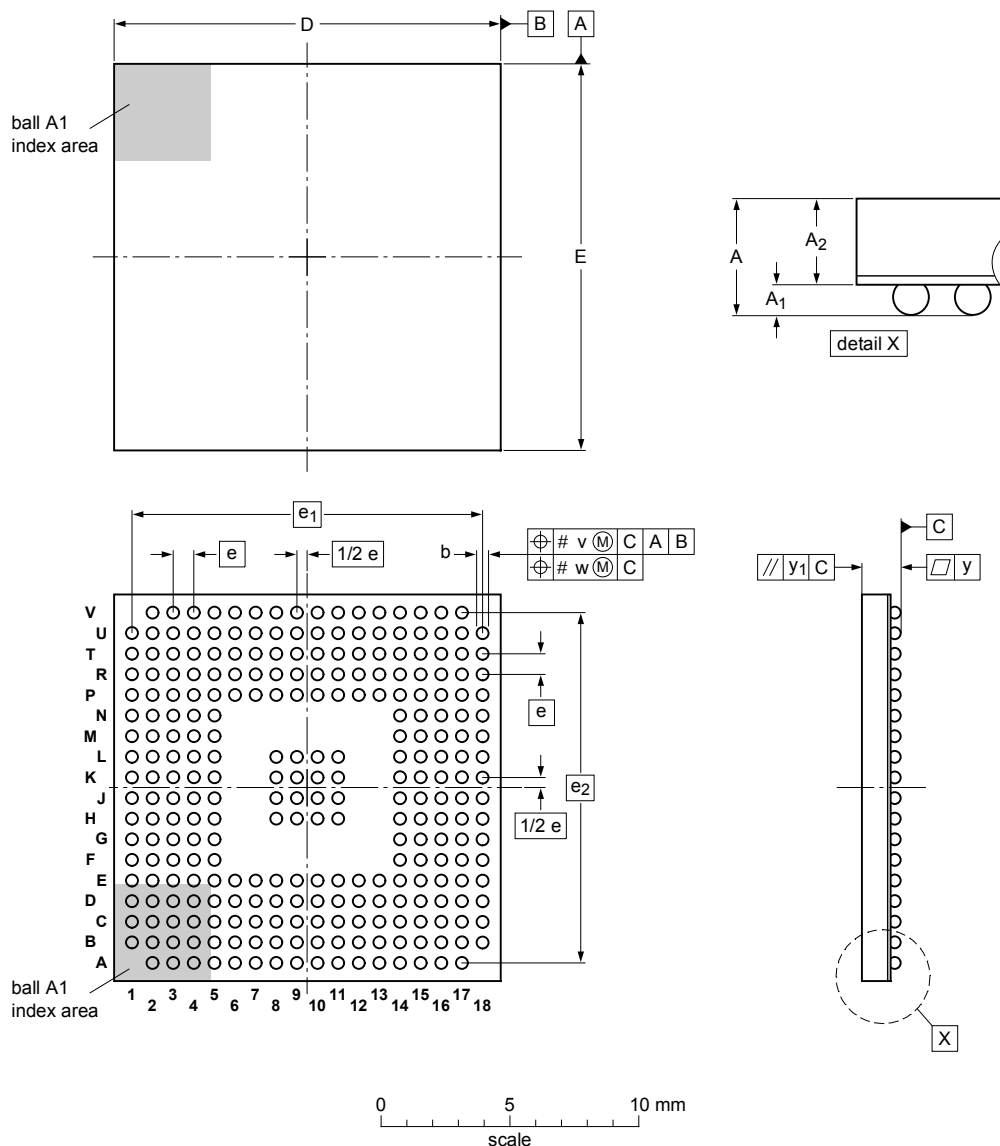


Fig. 1. Package outline LFBGA272 (SOT929-1)

3. Legal information

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4. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Legal information..... 3

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